



标准&定制开关连接器产品制造商
DONG GUAN XI BANG ELECTRONICS CO., LTD.

规格书

SPECIFICATION

CUSTOMER NAME	客户名称:	_____
CUSTOMER NO.	客户编号:	_____
SERIES	系列	线对板压接式连接器
MODEL NO.	型号:	XB-series
DRAWING NO.	图形号	Wire to Board Crimp style Connectors

If specification of this product meets your request, please confirm all the items of it and return to us with signature and stamp, it will be basis of our production and record. Thanks your cooperation in advance!

若此产品规格符合贵司要求，敬请确认此规格书内所有项目
并签名和盖章后回传给我司，以作我司产品制作之
依据和存档之用，多谢合作！

EXAMINE & APPROVAL 审批

APPROVE 接受	NOT APPROVE 不接受
SIGNATURE 签署 STAMP 盖章 DATE 日期	

PREPARED BY. 制表人	CHECKED BY. 校对	APPROVED BY. 审核	APPROVAL BY. 批准
<div style="border: 1px solid red; padding: 2px; text-align: center;">研发部</div> <div style="border: 1px solid red; padding: 2px; text-align: center;">戴海明</div> <div style="border: 1px solid red; padding: 2px; text-align: center;">2022. 06. 08</div>	<div style="border: 1px solid red; padding: 2px; text-align: center;">品质部</div> <div style="border: 1px solid red; padding: 2px; text-align: center;">黄自清</div> <div style="border: 1px solid red; padding: 2px; text-align: center;">2022. 06. 08</div>	<div style="border: 1px solid red; padding: 2px; text-align: center;">工程部</div> <div style="border: 1px solid red; padding: 2px; text-align: center;">庞军</div> <div style="border: 1px solid red; padding: 2px; text-align: center;">2022. 06. 08</div>	<div style="border: 1px solid red; padding: 2px; text-align: center;">总经办</div> <div style="border: 1px solid red; padding: 2px; text-align: center;">吴量</div> <div style="border: 1px solid red; padding: 2px; text-align: center;">2022. 06. 08</div>

东莞市溪榜电子有限公司

Dong guan Xi Bang Electronics Co., Ltd

地址: 广东省东莞市黄江镇合路工业区
Address: He Lu Industrial Zone, Huangjiang Town
, Dongguan City, Guangdong Province
Tel: (0769)82055138/82056828
Fax: (0769)83663452

邮箱: admin@alspr.com switch@alspr.com
<http://www.alspr.cn/> <http://www.alspr.com/>

Dong Guan XB Electronics Co., Ltd

AccountNumber: 705540238
BankName: Citibank N. A., HongKongBranch
Country/Region: Hong Kong
BankCode: 006
BankAddress: 3 Garden Road, Central, Hong Kong
SWIFT/BIC: CITIHKHX (CITIHKHXXXX*If 11 characters are required)

MAil: HK@ALPSR.CN XB@ALPSR.CN XB@ALPSR.COM
Quality core! Afterburner for Made in China!



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CI01 Series Connector System	SPEC.NO.: SPCI001N
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO: CI01 Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 0.8 mm (.031") ~ 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings

REVIEWED : XIE.BING.XIN APPROVED : HE.LONG.FEI VERIFIED : PANG.DONG .



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		2A 250V AC/DC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 800 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Wire size	Specified wire size	Accepts AWG#24~#30
8.2	Terminal crimp Tensile strength	When crimped AWG#24 size wire When crimped AWG#26 size wire When crimped AWG#28 size wire When crimped AWG#30 size wire	More than 3.0 Kgf More than 2.0 Kgf More than 1.3 Kgf More than 0.8 Kgf
8.3	Terminal insertion force	Insertion speed 25± 3 mm per minute into housing	Less than 600 gram
8.4	Contact retaining force in insulator	Retention speed 25± 3 mm per minute from housing	More than 1.5 Kgf
8.5	Single contact insertion force	Measure force to insertion using 0.50 mm square pin at speed 25± 3 mm per minute	700 gram max.
8.6	Single contact withdrawal force	Measure force to withdrawal using 0.50 mm square pin at speed 25± 3 mm per minute	100 gram min.
8.7	Durability	Connector shall be subjected to 30 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial
8.8	Pin retention force	Push pin from insulator base at speed 25± 3 mm per minute	More than 1.0 Kgf

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.



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	ITEM	TEST CONDITION	REQUIREMENT
9.3	Solder ability	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: $230 \pm 5^{\circ}\text{C}$ Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: $245 \pm 5^{\circ}\text{C}$	Minimum: 90% of immersed area
9.4	Resistance to soldering heat	DIP Type Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: $240 \pm 5^{\circ}\text{C}$ DIP Type Lead-Free Process Soldering time: 5 ± 0.5 second Soldering pot: $260 \pm 5^{\circ}\text{C}$ SMT Type Tin-Lead Process: Refer Reflow temperature profile(12.1) Soldering time: 10 second Max. Soldering pot: $230 \pm 5^{\circ}\text{C}$ SMT Type Lead-Free Process: Soldering time: 20 second Max. Soldering pot: $250\sim 260^{\circ}\text{C}$ Refer Reflow temperature profile(12.2)	No damage
9.5	Heat aging	$105 \pm 2^{\circ}\text{C}$, 96 hours	No damage
9.6	Humidity	$40 \pm 2^{\circ}\text{C}$, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.7	Temperature cycling	One cycle consists of : (1)- 55^{+0}_{-3} $^{\circ}\text{C}$, 30 min. (2)Room temp. 10-15 min. (3) 85^{+3}_{-0} $^{\circ}\text{C}$, 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial



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	ITEM	TEST CONDITION	REQUIREMENT
9.8	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -25 to + 105°C

11. Mating and Unmating Force:

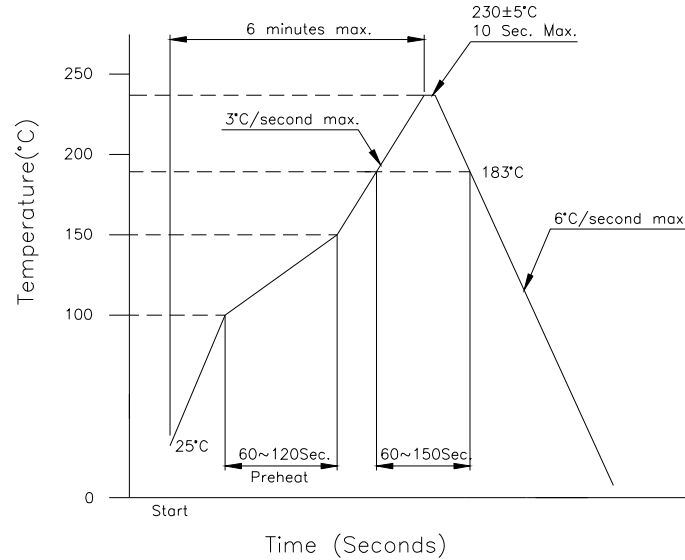
PIN No.	Mating(kgf max.)	Unmating(kgf min.)
2	1.5	0.3
3	3.0	0.6
4	3.0	0.6
5	4.0	1.0
6	4.0	1.0
7	5.0	1.2
8	5.0	1.2
9	5.0	1.2
10	6.0	1.4
11	6.0	1.4
12	6.0	1.4
13	7.0	1.8
14	8.0	2.0
15	10.0	2.5
16	10.0	2.5



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12. Recommended IR Reflow Temperature Profile:

12.1 Using Typical Solder Paste



12.2 Using Lead-Free Solder Paste

